What is claimed is:

An electromagnetic interference (EMI) suppression device for suppressing both common mode and differential mode noises, comprising:

a case;

a common mode noise reduction element accommodated in the case;

a plurality of conductive pillars, each penetrating through the case to form a connection pad; and

at least one differential mode noise reduction element fixed to the conductive pillar and electrically connected to the common mode noise reduction element; wherein

the EMI device is mounted onto a printed circuit board(PCB) via the connection pad.

- 2. The EMI suppression device as described in claim 1, wherein the common mode noise reduction element is a common mode choke.
- 3. The EMI suppression device as described in claim 1, wherein the differential mode noise reduction element is a ferrite bead.
- 4. The EMI suppression device as described in claim 1, wherein the case is made of plastic.

- 5. The EMI suppression device as described in claim 1, wherein the conductive pillars are made of metal.
- 6. The EMI suppression device as described in claim 1, wherein the differential mode noise reduction element is fixed to the conductive pillars by means of an adhesive.
- 7. The EMI suppression device as described in claim 1, wherein on the surface of the conductive pillar is formed with a notch.
- 8. An electromagnetic interference (EMI) suppression device for suppressing both common mode and differential mode noises, comprising:

a case having a housing and a plurality of foot portions protruding from the housing;

a common mode noise reduction element accommodated in the housing;

a plurality of conductive pillars, each penetrating through the case to form two separate portions, a mount and a connection pad; and

at least one differential mode noise reduction element fixed to the mounts of the conductive pillars and electrically connected to the common mode noise reduction element; wherein

the EMI device is mounted onto a PCB via the connection pads.

- 9. The EMI suppression device as described in claim 8, wherein the differential mode noise reduction element is fixed to the conductive pillars by means of an adhesive.
- 10. The EMI suppression device as described in claim 1, wherein on the surface of the conductive pillar is formed with a notch.